

PLASMA PROCESSING METHOD AND PLASMA PROCESSING SYSTEM

Abstract

A technique capable of improving a roughness of a surface of a metal-containing resist film formed on a substrate is provided. A substrate processing method includes (a) providing a substrate including an underlying film and a metal-containing resist film in which a pattern is formed on the underlying film; (b) forming a metal-containing film on a surface of the metal-containing resist film; and (c) removing a residue of the metal-containing film together with at least a part of the metal-containing film.

Fig. 3